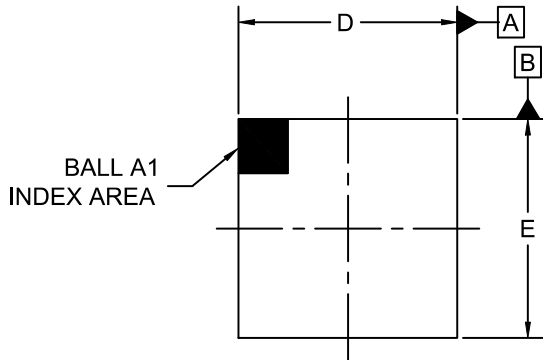
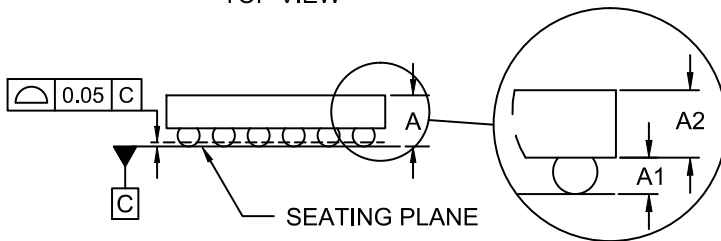


**WLCSP36 2.43x2.43x0.488**  
CASE 567WJ  
ISSUE A

DATE 03 OCT 2018



TOP VIEW



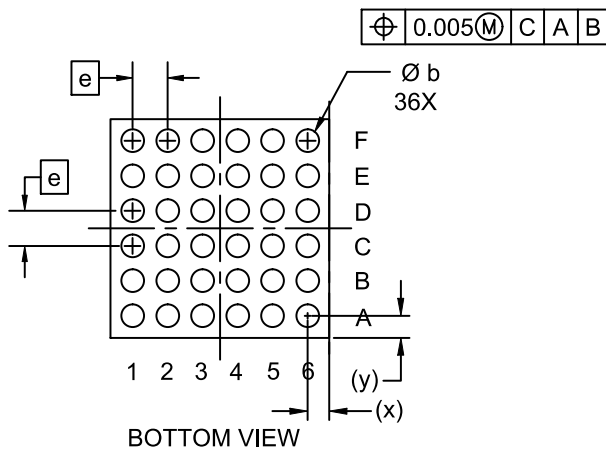
SIDE VIEW

DETAIL A

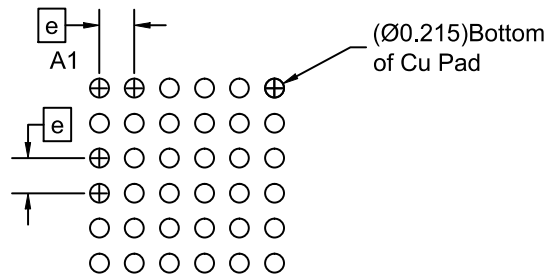
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.450	0.488	0.526
A1	0.176	0.196	0.216
A2	0.274	0.292	0.310
b	0.240	0.260	0.280
D	2.400	2.430	2.460
E	2.400	2.430	2.460
e	0.40 BSC		
x	0.200	0.215	0.230
y	0.200	0.215	0.230



BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT (NSMD PAD TYPE)

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<b>DESCRIPTION:</b>	<b>WLCSP36 2.43x2.43x0.488</b>	<b>PAGE 1 OF 1</b>

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